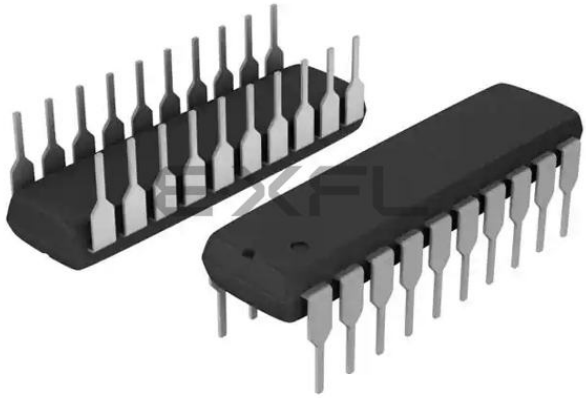

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	eZ8
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, LED, POR, PWM, WDT
Number of I/O	17
Program Memory Size	1KB (1K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Through Hole
Package / Case	20-DIP (0.300", 7.62mm)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8f0130ph020eg

Calibration and Compensation 101
ADC Control Register Definitions 101
ADC Control Register 0 102
ADC Data High Byte Register 103
ADC Data Low Bits Register 103
Sample Settling Time Register 104
Sample Time Register 105

Comparator 106
Operation 106
Comparator Control Register Definitions 107

Flash Memory 108
Data Memory Address Space 111
Flash Information Area 111
Operation 112
Flash Operation Timing Using the Flash Frequency Registers 114
Flash Code Protection Against External Access 114
Flash Code Protection Against Accidental Program and Erasure 114
Byte Programming 116
Page Erase 117
Mass Erase 117
Flash Controller Bypass 117
Flash Controller Behavior in Debug Mode 117
NVDS Operational Requirements 118
Flash Control Register Definitions 118
Flash Control Register 119
Flash Status Register 120
Flash Page Select Register 121
Flash Sector Protect Register 122
Flash Frequency High and Low Byte Registers 123

Flash Option Bits 124
Operation 124
Option Bit Configuration by Reset 124
Option Bit Types 125
Flash Option Bit Control Register Definitions 126
Trim Bit Address Register 126
Trim Bit Data Register 126
Flash Option Bit Address Space 127
Trim Bit Address Space 129

Nonvolatile Data Storage 134

Flash Control Register

The Flash Controller must be unlocked using the Flash Control Register before programming or erasing Flash memory. Writing the sequence 73H, 8CH, sequentially, to the Flash Control Register unlocks the Flash Controller. When the Flash Controller is unlocked, Flash memory can be enabled for mass erase or page erase by writing the appropriate enable command to the FCTL. Page erase applies only to the active page selected in Flash Page Select Register. Mass erase is enabled only through the On-Chip Debugger. Writing an invalid value or an invalid sequence returns the Flash Controller to its Locked state. The write-only Flash Control Register shares its register file address with the read-only Flash Status Register.

Table 72. Flash Control Register (FCTL)

Bit	7	6	5	4	3	2	1	0
Field	FCMD							
RESET	0	0	0	0	0	0	0	0
R/W	W	W	W	W	W	W	W	W
Address	FF8H							

Bit	Description
[7:0] FCMD	Flash Command 73H = First unlock command. 8CH = Second unlock command. 95H = Page erase command (must be third command in sequence to initiate page erase). 63H = Mass erase command (must be third command in sequence to initiate mass erase). 5EH = Enable Flash Sector Protect Register access.

ister, the user code must wait at least 5000 IPO cycles for the crystal to stabilize. After this period, the crystal oscillator may be selected as the system clock.

Figure 25 displays a recommended configuration for connection with an external fundamental-mode, parallel-resonant crystal operated at 20 MHz. Recommended 20 MHz crystal specifications are provided in Table 100. Resistor R_1 is optional and limits total power dissipation by the crystal. Printed circuit board layout must add no more than 4 pF of stray capacitance to either the X_{IN} or X_{OUT} pins. If oscillation does not occur, reduce the values of capacitors C_1 and C_2 to decrease loading.

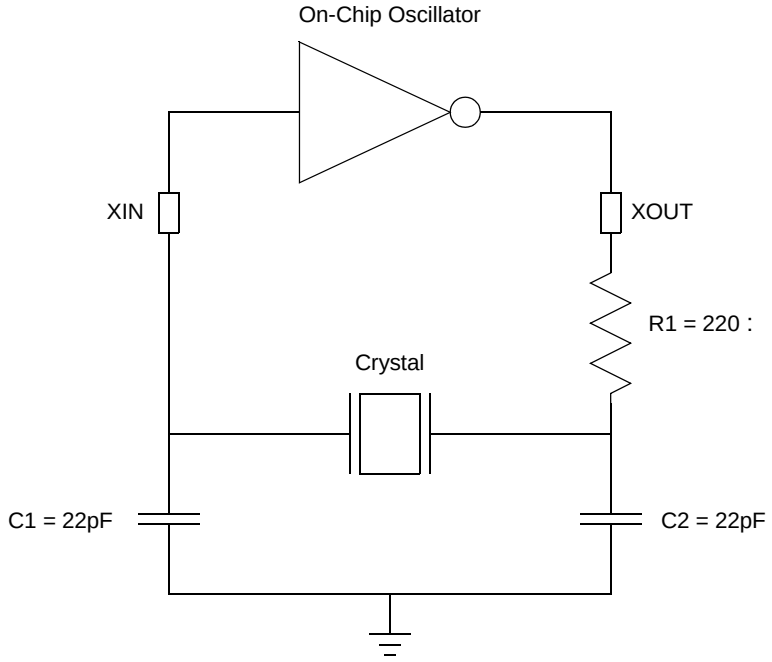

Figure 25. Recommended 20 MHz Crystal Oscillator Configuration

Table 100. Recommended Crystal Oscillator Specifications

Parameter	Value	Units	Comments
Frequency	20	MHz	
Resonance	Parallel		
Mode	Fundamental		
Series Resistance (R_S)	60	:	Maximum
Load Capacitance (C_L)	30	pF	Maximum
Shunt Capacitance (C_0)	7	pF	Maximum
Drive Level	1	mW	Maximum